



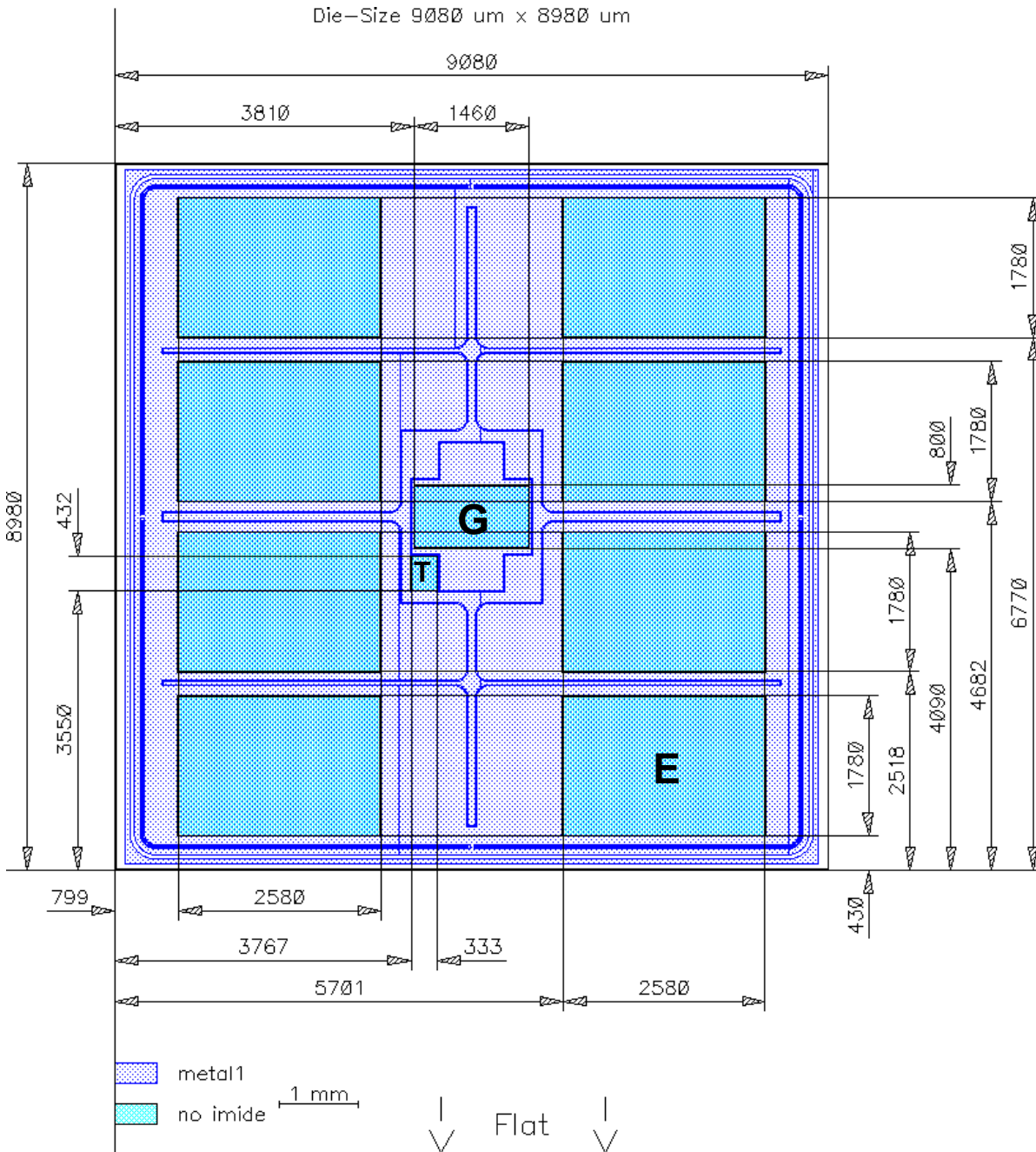
# SIGC81T120R2C

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## **Further Electrical Characteristic**

Switching characteristics and thermal properties are depending strongly on module design and mounting technology and can therefore not be specified for a bare die.

## Chip Drawing



**E** = Emitter pad

**G** = Gate pad

**T** = Test pad do not contact